TOSHIBA Photo-interrupter Infrared LED+Phototransistor

TLP1243(C8)

Copiers, Printers and Fax Machines Fanheaters and Air-conditioners Bank Atms Game Machines

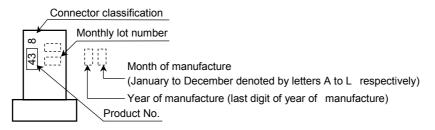
The TLP1243 (C8) is a compact photointerrupter with a built-in connector, which uses a GaAs infrared LED and an Si phototransistor.

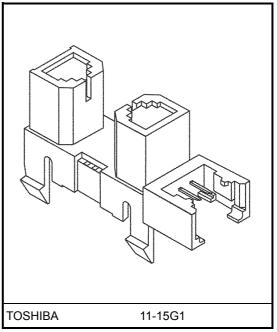
• Small package

Compared to Toshiba TLP1241 (C5), the volume and the mounting area of the TLP1243 (C8) are reduced to 70% and 75% respectively.

- Three board thicknesses supported: 1.0 mm, 1.2 mm and 1.6 mm
- Gap: 5 mm
- Resolution: Slit width = 0.7 mm
- High-temperature operation: T_{opr} = 95°C (max)
- Current transfer ratio: IC/IF = 2.5% (min)
- Mini CT connector (1.5-mm pitch MT RECEPTACLE ASSEMBLY/HOUSING CRIMP TYPE) made by Tyco Electronics AMP, Ltd.
- Package and connector material: Polycarbonate (UL94V-2)
- Mounted with lead-free soldering alloys.

Marking





Weight: 0.8 g (typ.)

Maximum Ratings (Ta = 25°C)

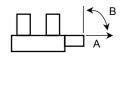
Characteristics		Symbol	Rating	Unit
	Forward current	١ _F	30	mA
LED	Forward current derating (Ta>25°C)	ΔI _F /°C	-0.28	mA/°C
	Reverse voltage	V _R	5	V
	Collector-emitter voltage	V _{CEO}	35	V
۲.	Emitter-collector voltage	V _{ECO}	5	V
Detector	Collector power dissipation	P _C	75	mW
Det	Collector power dissipation derating (Ta>25°C)	∆P _C /°C	-1	mW/°C
	Collector current	Ι _C	50	mA
Operating temperature range		T _{opr}	-30 to 95	°C
Storage temperature range		T _{stg}	-40 to 100	°C

Optical and Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test conditions	Min	Тур.	Max	Unit
	Forward voltage	V _F	I _F = 10 mA	1.00	1.18	1.40	V
LED	Reverse current	I _R	$V_R = 5 V$	_	—	10	μA
	Peak emission wavelength	λ _P	I _F = 10 mA		940		nm
Detector	Dark current	I _D (I _{CEO})	$V_{CE} = 24 \text{ V}, I_F = 0$		0.001	0.1	μA
	Peak sensitivity wavelength	λ _P	—		870		nm
	Current transfer ratio	I _C /I _F	$V_{CE} = 2 V, I_F = 10 mA$	2.5	—	100	%
Coupled	Collector-emitter saturation voltage	V _{CE (sat)}	I _F = 20 mA, I _C = 0.25 mA	_	0.1	0.35	V
	Rise time	tr	$V_{CE} = 5 V, I_{C} = 1 \text{ mA}, R_{I} = 1 \text{ k}\Omega$	_	15	50	
	Fall time	t _f	$v_{\text{CE}} = 0$ v, $v_{\text{C}} = 1$ mA, $N_{\text{L}} = 1$ Ns2	_	15	50	μS

Pin Strength (Ta = 25°C)

Characteristics	Test	conditions	Limit	
	Direction	А		
Pulling	Weight	19.6N		
	Time	5 s/once	No defect in electrical	
	Direction	В	characteristics	
Bending	Weight	9.8N		
	Time	5 s/three times		



Recommended Connector

Mini CT connector (1.5-mm pitch, MT RECEPTACLE ASSEMBLY/HOUSING CRIMP TYPE) made by Tyco Electronics AMP, Ltd.

	Туре	Model Number	Terminal Material	AWG Size	External Diameter of Insulation Coating
Housing-Terminal En Block Type	MT RECEPTACLE ASSEMBLY	353293-3	Phosphor bronze	AWG26 to 28	0.85 mm to 0.95 mm
	HOUSING CRIMP TYPE	353908-3			

Note: For more of connector characteristics, please contact the relevant connector manufacturer.

Precautions

- Keep the device away from external light. Although the photo-IC is of low optical sensitivity, the device may malfunction if external light with a wavelength of 700 nm or more is allowed to impinge on it.
- Care must be taken in relation to the environment in which the device is to be installed. Oil or chemicals may cause the package to melt or crack.
- When attaching the device to the metal board, always hold the body of the device. Do not hold it by the connector. Ensure that the board is flat, and not warped or twisted. Attach the device to a metal board at room temperature.
- Toshiba recommends attaching the device to the smoother side of the board.
- Toshiba recommends testing the attachment strength beforehand by actually attaching a device to the board.
- Do not apply solder to the pins of the device's connector. Make sure that the connector is plugged into the Mini CT connector or equivalent connector.
- When inserting or removing the Mini CT connector or equivalent connector, always grasp it and its cable firmly and either plug it straight into or pull it straight out of the device's connector. If the Mini CT connector or equivalent connector is inserted or removed at an angle, both the device's connector and the Mini CT connector or equivalent connector may get damaged, resulting in an unreliable connection.
- Conversion efficiency falls over time due to the current which flows in the infrared LED. When designing a circuit, take into account this change in conversion efficiency over time. The ratio of fluctuation in conversion efficiency to fluctuation in infrared LED optical output is 1:1.

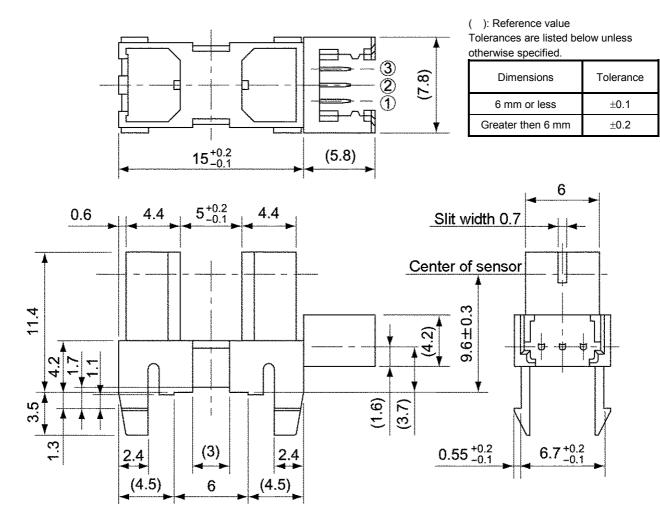
$$\frac{\mathrm{IC/IF}\left(\mathrm{t}\right)}{\mathrm{IC/IF}\left(\mathrm{0}\right)}=\frac{\mathrm{P_{0}}\left(\mathrm{t}\right)}{\mathrm{P_{0}}\left(\mathrm{0}\right)}$$

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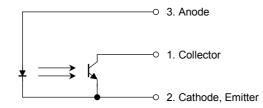
TLP1243(C8)

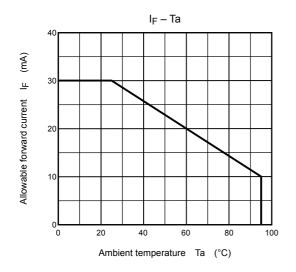
Package Dimensions: TOSHIBA 11-15G1

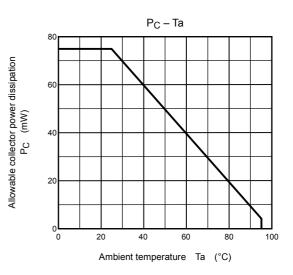
Unit: mm

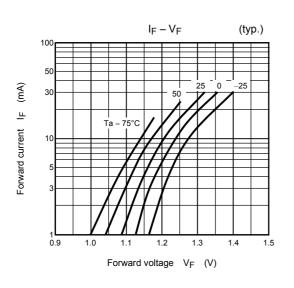


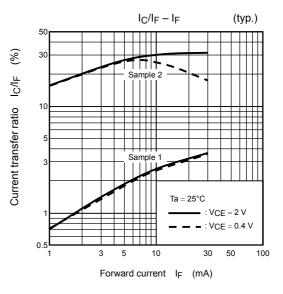
Pin Connection

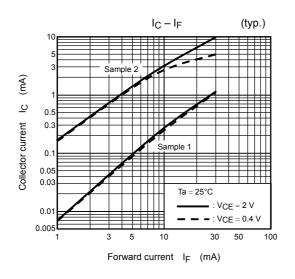


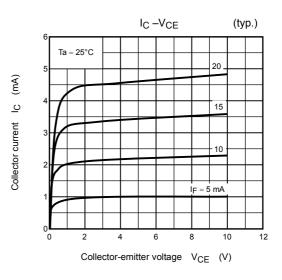


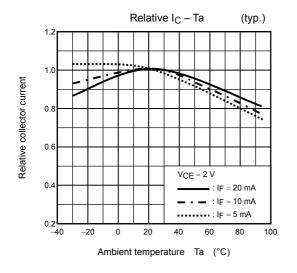


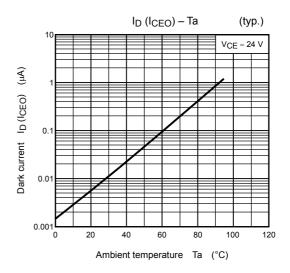






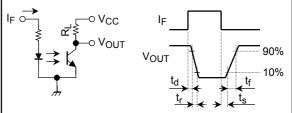


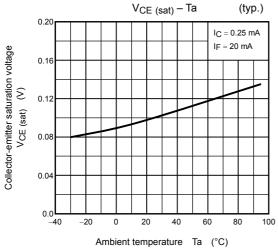


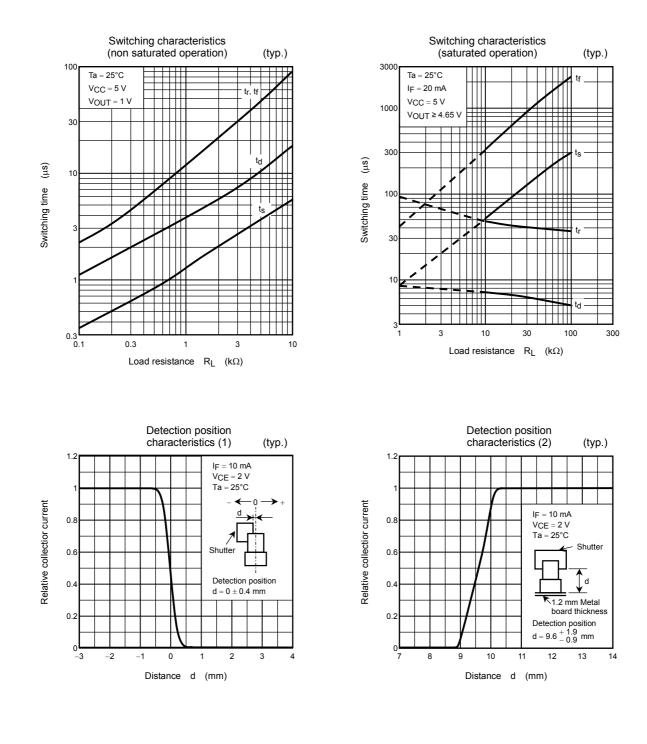


 $I_{C} = 0.25 \text{ mA}$ $I_{F} = 20 \text{ mA}$ $I_{F} = 20 \text{ mA}$



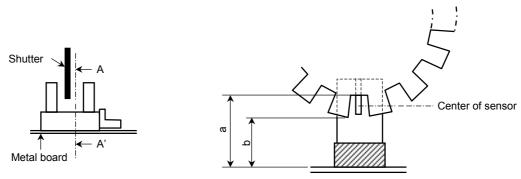






Relative Positioning of Shutter and Device

For normal operation, position the shutter and the device as shown in the figure below. By considering the device's detection direction characteristic and switching time, determine the shutter slit width and pitch.

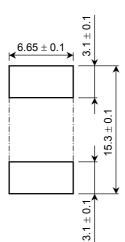


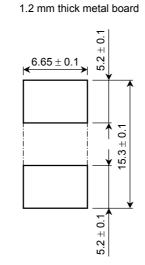
Cross section between A and A'

_		Unit: mm
Thickness of Metal Board	a Dimension	b Dimension
1.0	11.7 min	8.9 max
1.2	11.5 min	8.7 max
1.6	11.1 min	8.3 max

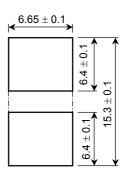
Recommended Size of Connection Holes (Unit: mm)

1.0 mm thick metal board





1.6 mm thick metal board



RESTRICTIONS ON PRODUCT USE

Handbook" etc.,

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